



January 2001
Revised August 2001

74LCX32374

Low Voltage 32-Bit D-Type Flip-Flop with 5V Tolerant Inputs and Outputs (Preliminary)

General Description

The LCX32374 contains thirty-two non-inverting D-type flip-flops with 3-STATE outputs and is intended for bus oriented applications. The device is byte controlled. A buffered clock (CP) and Output Enable (\overline{OE}) are common to each byte and can be shorted together for full 32-bit operation.

The LCX32374 is designed for low voltage (2.5V or 3.3V) V_{CC} applications with capability of interfacing to a 5V signal environment.

The LCX32374 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

Features

- 5V tolerant inputs and outputs
- 2.3V–3.6V V_{CC} specifications provided
- 6.2 ns t_{PD} max ($V_{CC} = 3.3V$), 20 μA I_{CC} max
- Power down high impedance inputs and outputs
- Supports live insertion/withdrawal (Note 1)
- ± 24 mA output drive ($V_{CC} = 3.0V$)
- Uses patented noise/EMI reduction circuitry
- Latch-up performance exceeds 500 mA
- ESD performance:
 - Human body model > 2000V
 - Machine model > 200V
- Packaged in plastic Fine-Pitch Ball Grid Array (FBGA) (Preliminary)

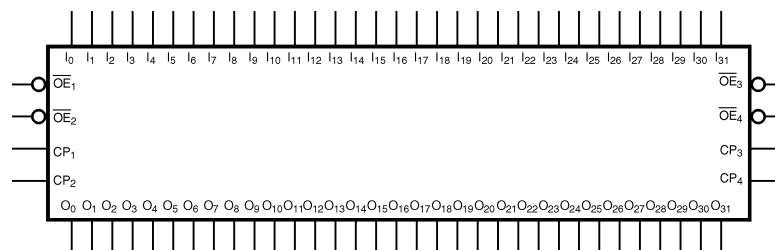
Note 1: To ensure the high-impedance state during power up or down, \overline{OE} should be tied to V_{CC} through a pull-up resistor: the minimum value or the resistor is determined by the current-sourcing capability of the driver.

Ordering Code:

Order Number	Package Number	Package Description
74LCX32374GX (Note 2)	BGA96A (Preliminary)	96-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide [Tape and Reel]

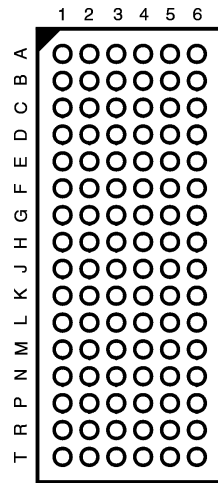
Note 2: BGA device available in Tape and Reel only.

Logic Symbol



74LCX32374 Low Voltage 32-Bit D-Type Flip-Flop with 5V Tolerant Inputs and Outputs (Preliminary)

Connection Diagram



(Top Thru View)

Functional Description

The LCX32374 consists of thirty-two edge-triggered flip-flops with individual D-type inputs and 3-STATE true outputs. The device is byte controlled with each byte functioning identically, but independent of the other. The control pins can be shorted together to obtain full 32-bit operation. Each byte has a buffered clock and buffered Output Enable common to all flip-flops within that byte. The description which follows applies to each byte. Each flip-flop will store the state of their individual D inputs that meet the setup and hold time requirements on the LOW-to-HIGH Clock (CP_n) transition. With the Output Enable (\overline{OE}_n) LOW, the contents of the flip-flops are available at the outputs. When \overline{OE}_n is HIGH, the outputs go to the high impedance state. Operation of the \overline{OE}_n input does not affect the state of the flip-flops.

Pin Descriptions

Pin Names	Description
\overline{OE}_n	Output Enable Input (Active LOW)
CP_n	Clock Pulse Input
I_0-I_{31}	Inputs
O_0-O_{31}	Outputs

FBGA Pin Assignments

	1	2	3	4	5	6
A	O_1	O_0	\overline{OE}_1	CP_1	I_0	I_1
B	O_3	O_2	GND	GND	I_2	I_3
C	O_5	O_4	V_{CC}	V_{CC}	I_4	I_5
D	O_7	O_6	GND	GND	I_6	I_7
E	O_9	O_8	GND	GND	I_8	I_9
F	O_{11}	O_{10}	V_{CC}	V_{CC}	I_{10}	I_{11}
G	O_{13}	O_{12}	GND	GND	I_{12}	I_{13}
H	O_{14}	O_{15}	\overline{OE}_2	CP_2	I_{15}	I_{14}
J	O_{17}	O_{16}	\overline{OE}_3	CP_3	I_{16}	I_{17}
K	O_{19}	O_{18}	GND	GND	I_{18}	I_{19}
L	O_{21}	O_{20}	V_{CC}	V_{CC}	I_{20}	I_{21}
M	O_{23}	O_{22}	GND	GND	I_{22}	I_{23}
N	O_{25}	O_{24}	GND	GND	I_{24}	I_{25}
P	O_{27}	O_{26}	V_{CC}	V_{CC}	I_{26}	I_{27}
R	O_{29}	O_{28}	GND	GND	I_{28}	I_{29}
T	O_{30}	O_{31}	\overline{OE}_4	CP_4	I_{31}	I_{30}

Truth Table

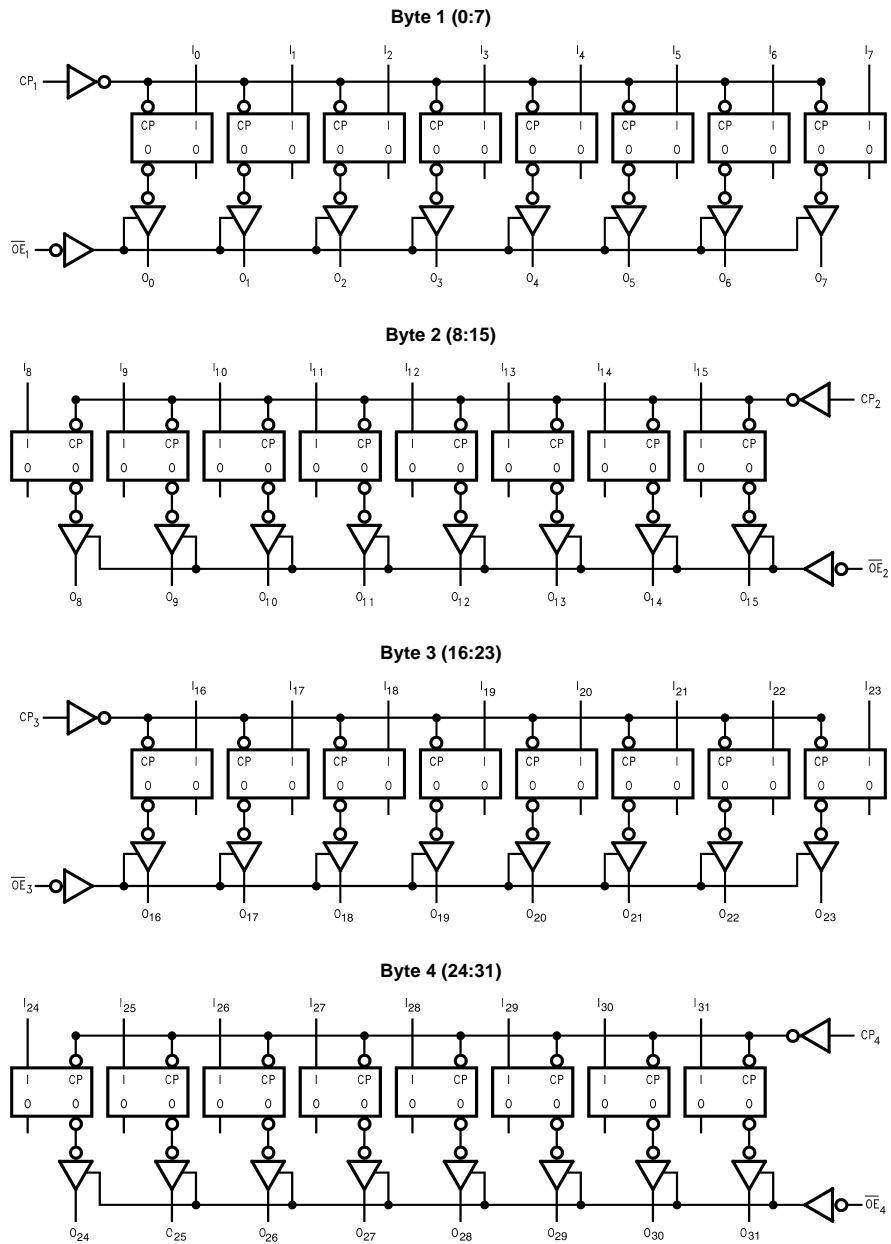
Inputs			Outputs
CP_n	\overline{OE}_n	I_n	O_n
	L	H	H
	L	L	L
L	L	X	O_0
X	H	X	Z

X = Immaterial

Z = High Impedance

 O_0 = Previous O_0 before HIGH-to-LOW of CP

Logic Diagrams



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings(Note 3)

Symbol	Parameter	Value	Conditions	Units
V_{CC}	Supply Voltage	-0.5 to +7.0		V
V_I	DC Input Voltage	-0.5 to +7.0		V
V_O	DC Output Voltage	-0.5 to +7.0 -0.5 to $V_{CC} + 0.5$	3-STATE Output in HIGH or LOW State (Note 4)	V
I_{IK}	DC Input Diode Current	-50	$V_I < \text{GND}$	mA
I_{OK}	DC Output Diode Current	-50 +50	$V_O < \text{GND}$ $V_O > V_{CC}$	mA
I_O	DC Output Source/Sink Current	± 50		mA
I_{CC}	DC Supply Current per Supply Pin	± 100		mA
I_{GND}	DC Ground Current per Ground Pin	± 100		mA
T_{STG}	Storage Temperature	-65 to +150		°C

Recommended Operating Conditions (Note 5)

Symbol	Parameter	Min	Max	Units
V_{CC}	Supply Voltage			
	Operating	2.0	3.6	V
	Data Retention	1.5	3.6	V
V_I	Input Voltage	0	5.5	V
V_O	Output Voltage			
	HIGH or LOW State	0	V_{CC}	V
	3-STATE	0	5.5	V
I_{OH}/I_{OL}	Output Current			
	$V_{CC} = 3.0V - 3.6V$		± 24	mA
	$V_{CC} = 2.7V - 3.0V$		± 12	mA
	$V_{CC} = 2.3V - 2.7V$		± 8	mA
T_A	Free-Air Operating Temperature	-40	85	°C
$\Delta t/\Delta V$	Input Edge Rate, $V_{IN} = 0.8V - 2.0V$, $V_{CC} = 3.0V$	0	10	ns/V

Note 3: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 4: I_O Absolute Maximum Rating must be observed.

Note 5: Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Symbol	Parameter	Conditions	V_{CC} (V)	$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$		Units
				Min	Max	
V_{IH}	HIGH Level Input Voltage		2.3 - 2.7 2.7 - 3.6	1.7 2.0		V
V_{IL}	LOW Level Input Voltage		2.3 - 2.7 2.7 - 3.6		0.7 0.8	V
V_{OH}	HIGH Level Output Voltage	$I_{OH} = -100 \mu\text{A}$ $I_{OH} = -8 \text{ mA}$ $I_{OH} = -12 \text{ mA}$ $I_{OH} = -18 \text{ mA}$ $I_{OH} = -24 \text{ mA}$	2.3 - 3.6 2.3 2.7 3.0 3.0	$V_{CC} - 0.2$ 1.8 2.2 2.4 2.2		V
V_{OL}	LOW Level Output Voltage	$I_{OL} = 100 \mu\text{A}$ $I_{OL} = 8 \text{ mA}$ $I_{OL} = 12 \text{ mA}$ $I_{OL} = 16 \text{ mA}$ $I_{OL} = 24 \text{ mA}$	2.3 - 3.6 2.3 2.7 3.0 3.0		0.2 0.6 0.4 0.4 0.55	V
I_I	Input Leakage Current	$0 \leq V_I \leq 5.5V$	2.3 - 3.6		± 5.0	μA
I_{OZ}	3-STATE Output Leakage	$0 \leq V_O \leq 5.5V$ $V_I = V_{IH}$ or V_{IL}	2.3 - 3.6		± 5.0	μA
I_{OFF}	Power-Off Leakage Current	V_I or $V_O = 5.5V$	0		10	μA

DC Electrical Characteristics (Continued)

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = -40°C to +85°C		Units
				Min	Max	
I _{CC}	Quiescent Supply Current	V _I = V _{CC} or GND	2.3 – 3.6		20	μA
		3.6V ≤ V _I , V _O ≤ 5.5V (Note 6)	2.3 – 3.6		±20	
ΔI _{CC}	Increase in I _{CC} per Input	V _{IH} = V _{CC} - 0.6V	2.3 – 3.6		500	μA

Note 6: Outputs disabled or 3-STATE only.

AC Electrical Characteristics

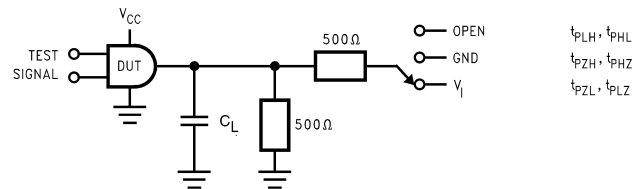
Symbol	Parameter	T _A = -40° to +85°C, R _L = 500Ω						Units
		V _{CC} = 3.3V ± 0.3V		V _{CC} = 2.7V		V _{CC} = 2.5V ± 0.2V		
		C _L = 50 pF		C _L = 50 pF		C _L = 30 pF		
		Min	Max	Min	Max	Min	Max	
f _{MAX}	Maximum Clock Frequency	170						MHz
t _{PHL}	Propagation Delay	1.5	6.2	1.5	6.5	1.5	7.4	ns
t _{PLH}	CP to O _n	1.5	6.2	1.5	6.5	1.5	7.4	
t _{PZL}	Output Enable time	1.5	6.1	1.5	6.3	1.5	7.9	ns
t _{PZH}		1.5	6.1	1.5	6.3	1.5	7.9	
t _{PLZ}	Output Disable Time	1.5	6.0	1.5	6.2	1.5	7.2	ns
t _{PHZ}		1.5	6.0	1.5	6.2	1.5	7.2	
t _S	Setup Time	2.5		2.5		3.0		ns
t _H	Hold Time	1.5		1.5		2.0		ns
t _W	Pulse Width	3.0		3.0		3.5		ns

Dynamic Switching Characteristics

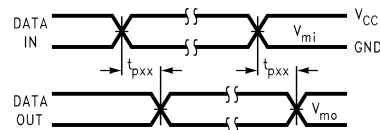
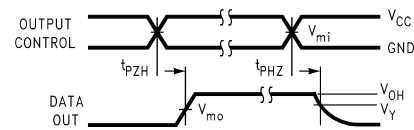
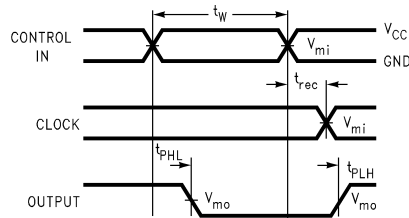
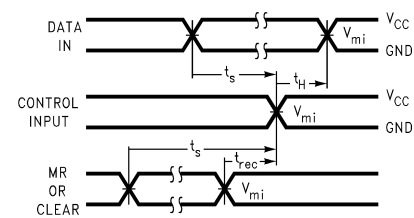
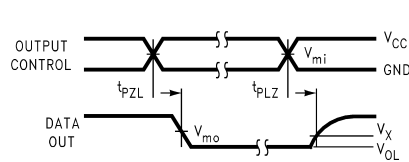
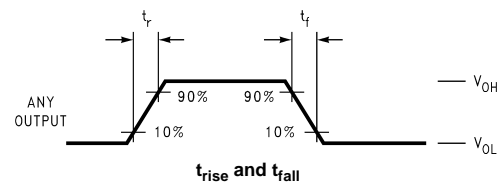
Symbol	Parameter	Conditions	V _{CC} (V)	T _A = 25°C	Units
				Typical	
V _{OLP}	Quiet Output Dynamic Peak V _{OL}	C _L = 50 pF, V _{IH} = 3.3V, V _{IL} = 0V	3.3	0.8	V
		C _L = 30 pF, V _{IH} = 2.5V, V _{IL} = 0V	2.5	0.6	
V _{OLV}	Quiet Output Dynamic Valley V _{OL}	C _L = 50 pF, V _{IH} = 3.3V, V _{IL} = 0V	3.3	-0.8	V
		C _L = 30 pF, V _{IH} = 2.5V, V _{IL} = 0V	2.5	0.6	

Capacitance

Symbol	Parameter	Conditions	Typical	Units
C _{IN}	Input Capacitance	V _{CC} = Open, V _I = 0V or V _{CC}	7	pF
C _{OUT}	Output Capacitance	V _{CC} = 3.3V, V _I = 0V or V _{CC}	8	pF
C _{PD}	Power Dissipation Capacitance	V _{CC} = 3.3V, V _I = 0V or V _{CC} , f = 10 MHz	20	pF

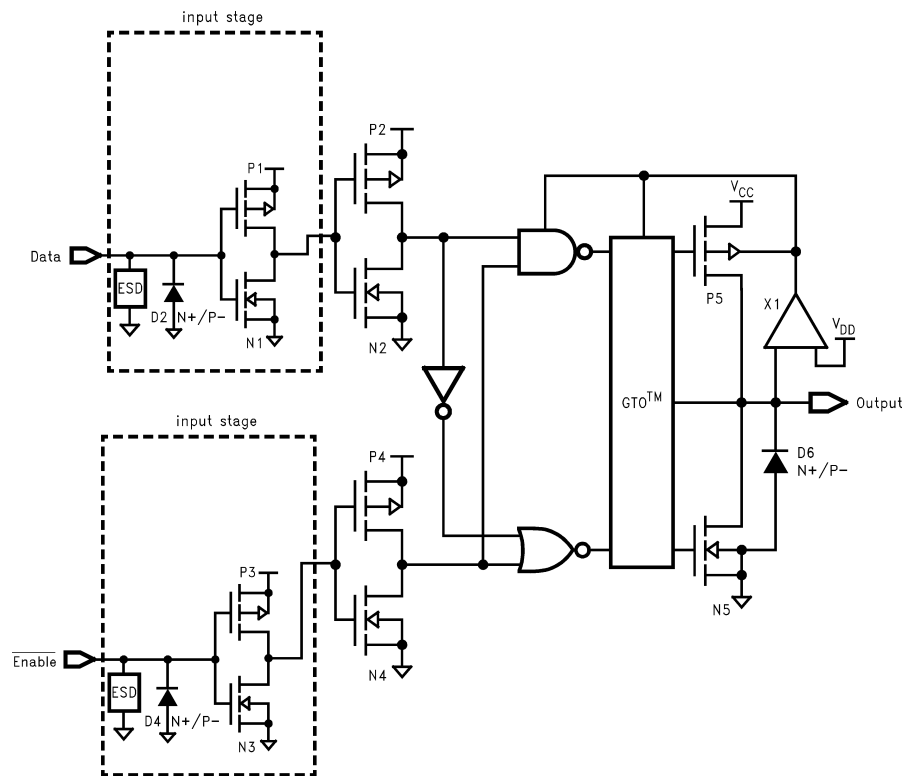
AC LOADING and WAVEFORMS Generic for LCX Family**FIGURE 1. AC Test Circuit (C_L includes probe and jig capacitance)**

Test	Switch
t_{PLH} , t_{PHL}	Open
t_{PZL} , t_{PLZ}	6V at $V_{CC} = 3.3 \pm 0.3V$, and 2.7V $V_{CC} \times 2$ at $V_{CC} = 2.5 \pm 0.2V$
t_{PZH} , t_{PHZ}	GND

**Waveform for Inverting and Non-Inverting Functions****3-STATE Output High Enable and Disable Times for Logic****Propagation Delay, Pulse Width and t_{rec} Waveforms****Setup Time, Hold Time and Recovery Time for Logic****3-STATE Output Low Enable and Disable Times for Logic****FIGURE 2. Waveforms
(Input Characteristics; $f = 1MHz$, $t_r = t_f = 3ns$)**

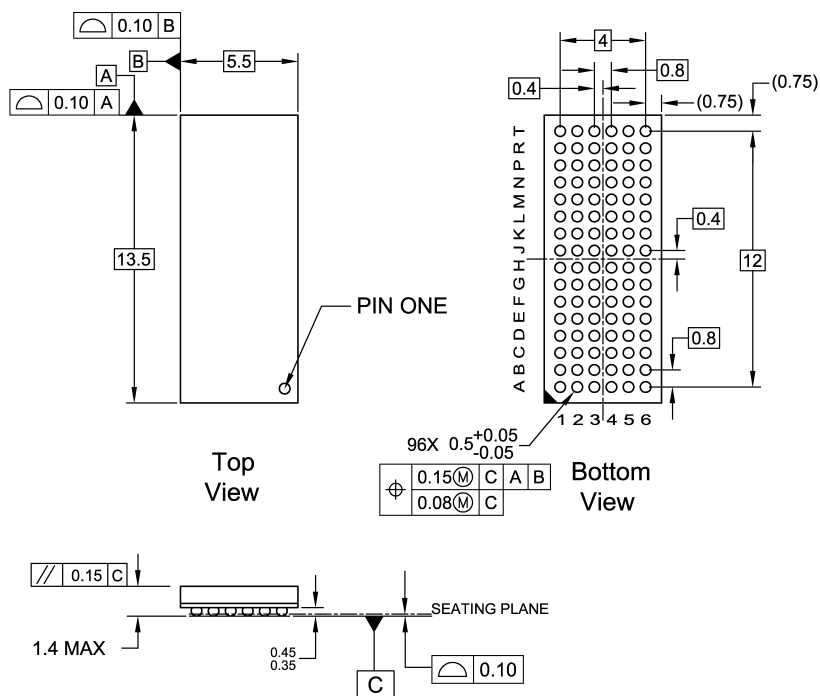
Symbol	V_{CC}		
	$3.3V \pm 0.3V$	2.7V	$2.5V \pm 0.2V$
V_{mi}	1.5V	1.5V	$V_{CC}/2$
V_{mo}	1.5V	1.5V	$V_{CC}/2$
V_x	$V_{OL} + 0.3V$	$V_{OL} + 0.3V$	$V_{OL} + 0.15V$
V_y	$V_{OH} - 0.3V$	$V_{OH} - 0.3V$	$V_{OH} - 0.15V$

Schematic Diagram Generic for LCX Family



Preliminary

Physical Dimensions inches (millimeters) unless otherwise noted



NOTES:

- A. THIS PACKAGE CONFORMS TO JEDEC MO-205
- B. ALL DIMENSIONS IN MILLIMETERS
- C. LAND PATTERN RECOMMENDATION: NSMD (Non Solder Mask Defined)
.35MM DIA PADS WITH A SOLDERMASK OPENING OF .45MM CONCENTRIC TO PADS
- D. DRAWING CONFORMS TO ASME Y14.5M-1994

BGA96ArevE

96-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide
Package Number BGA96A
Preliminary

Fairchild does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and Fairchild reserves the right at any time without notice to change said circuitry and specifications.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

www.fairchildsemi.com